

Application Data Sheet**Application Information**

Application Type::	National Phase
Subject Matter::	Utility
CD-ROM or CD-R:	None
Title::	WAFER DOUBLE-SIDE POLISHING APPARATUS AND DOUBLE-SIDE POLISHING METHOD
Attorney Docket Number::	120214
Suggested Drawing Figure::	
Total Drawing Sheets::	10
Small Entity::	No

Applicant Information

Applicant Authority type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Hiroyoshi
Family Name::	TOMINAGA
City of Residence::	Fukushima
Country of Residence::	JAPAN

Applicant Authority type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Toshiyuki
Family Name::	HAYASHI
City of Residence::	Gunma
Country of Residence::	JAPAN

Correspondence Information

10/500278

DT04 Rec'd PCT/PTO 29 JUN 2004

Correspondence Customer Number:: 25944

Domestic Priority Information			
Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application is a	National Stage of	PCT/JP03/03743	3/26/2003
Foreign Priority Information			
Country::	Application Number::	Filing Date::	Priority Claimed::
JAPAN	2002-91087	3/28/2002	Yes
Country::	Application Number::	Filing Date::	Priority Claimed::
JAPAN	2002-91207	3/28/2002	Yes
Assignee Information			
Assignee Name::		SHIN-ETSU HANDOTAI CO., LTD.	
Street of mailing address::		4-2, Marunouchi 1-chome, Chiyoda-ku,	
City of mailing address::		Tokyo,	
Country of mailing address::		JAPAN	